Title: Datasheet for MSP430FR2433 Customer Contact: PCN Manager Dept: Quality Services Change Type: Design Wafer Bump Site Assembly Site Detsign Wafer Bump Site Assembly Process Data Sheet Wafer Bump Material Assembly Materials Part number change Wafer Bump Process Mechanical Specification Test Site Wafer Fab Site Packing/Shipping/Labeling Test Process Wafer Fab Materials Description of Change: Wafer Fab Process Wafer Fab Process Notification Details Description. MsP430FR2433 Stasesoport datasheet(s) is being updated as summarized below. MsP430FR2433 Stasesoport exists MsP430FR2433 Stasesoport exists		
Change Type:		
Assembly Site Design Wafer Bump Site Assembly Process Data Sheet Wafer Bump Material Assembly Materials Part number change Wafer Bump Process Mechanical Specification Test Site Wafer Fab Site Packing/Shipping/Labeling Test Process Wafer Fab Materials Wafer Fab Process Wafer Fab Process Notification Details Description of Change: Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details. Image: Texas Instruments Image: Texas Instruments MSP430FR2433 SLASE59D - OCTOBER 2015-REVISED SEPTEMBER 2018 Page Changes from August 29, 2018 to September 10, 2018 Page Removed SYNC signal (not supported) from Figure 4-1, 32-Pin RHB Package (Top View) Combined two YQW pinout figures into one, and removed SYNC signal (not supported) in Figure 4-2, 24-Pin		
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YQW Package (Top and Bottom Views)		
Removed SYNC signal (not supported) from figure and table in Section 6.11.2, Port P2 (P2.0 to P2.2)		
Input/Output With Schmitt Trigger		
The datasheet number will be changing.		
Device Family Change From: Change To:		
MSP430FR2433 SLASE59C SLASE59D		
These changes may be reviewed at the datasheet links provided.		
http://www.ti.com/product/MSP430FR2433		
Reason for Change:		
To accurately reflect device characteristics.		
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):		
No anticipated impact. This is a specification change announcement only. There are no changes to		
the actual device.		
Changes to product identification resulting from this PCN:		
None.		
Product Affected:		
MSP430FR2433IRGER MSP430FR2433IRGET MSP430FR2433IYQWR MSP430FR2433IYQWT		
For questions regarding this notice, e-mails can be sent to the regional contacts shown below		
or your local Field Sales Representative.		
Location E-Mail		

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